

Features

- For surface mounted applications in order to optimize board
- space Low profile package
- Built-in strain relief
- Glass passivated junction
- Low inductance
- Excellent clamping capability
- 1500W peak pulse power capability at 10/1000µs waveform,
- repetition rate (duty cycle): 0.01%
- Fast response time
- Typical IR less than 1µA above 10V



SMC (DO-214AB)

Mechanical Data

- Case: JEDEC SMC(DO-214AB) molded plastic body
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbol marking on body Mounting
- Position: Any
- Weight: 0.003 ounce, 0.095 grams

Applications

- I/O interface
- AC/DC power supply
- Low frequency signal transmission line (RS232,RS485,etc.)

Maximum Ratings (Ta=25°C unless otherwise noted)

Peak pulse power dissipation at 10/1000µs waveform (Note1, Note2, Fig.1)	P _{PPM}	1500	W
Peak pulse current	I _{PP}	31	А
Steady state power dissipation at T _A =50 °C (Fig.5)	P _{M(AV)}	6.5	W
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load, (JEDEC Method) (Note3, Fig.6)	I _{FSM}	I _{FSM} 200	
Operating junction and Storage Temperature Range.	T_{J},T_{STG}	-65 to +150	°C
Typical thermal resistance junction to lead	R _{θJL}	15	°C/W
Typical thermal resistance junction to ambient	R _{θJA}	75	°C/W

Notes:1. Non-repetitive current pulse, per Fig.3 and derated above TA=25℃ per Fig.2.

Electrical Characteristics (Ta=25°C)

Part Num	ber	Mar	vice king ode	Reverse Stand- Off Voltage	Breakdown Voltage @I⊤	Test Current	Maximum Clamping Voltage @IPP	Peak Pulse Current	Reverse Leakage @VRWM
Unidirectional	Bidirectional	UNI	ВІ	VRWM(V)	VBR(V)	I⊤(mA)	Vc(V)	IPP(A)	Ir(µA)
SMCJ30AHE3_A/H	SMCJ30CAHE3_A/H	GFK	BFK	30.0	33.3-36.8	1	48.4	31.0	1

^{2.} Mounted on 5.0mm×5.0mm (0.03mm thick) copper pads to each terminal.

^{3. 8.3}ms single half sine-wave, or equivalent square wave, duty cycle=4 pulses per minutes maximum.



Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1. Peak Pulse Power Rating Curve

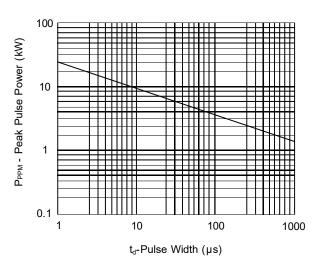


Figure 3. Pulse Waveform

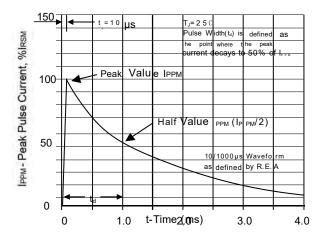


Figure 5. Steady State Power Dissipation Derating Curve

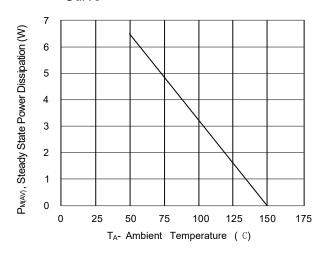


Figure 2. Pulse Derating Curve

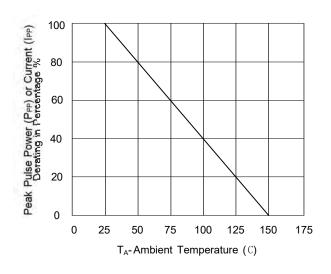


Figure 4. Typical Junction Capacitance

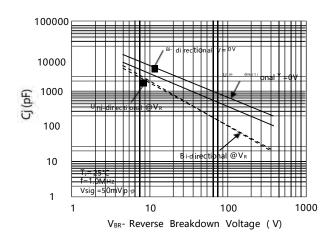
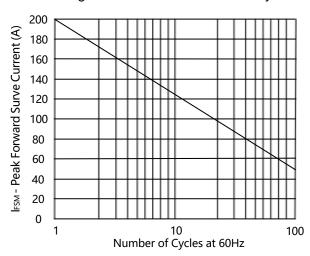
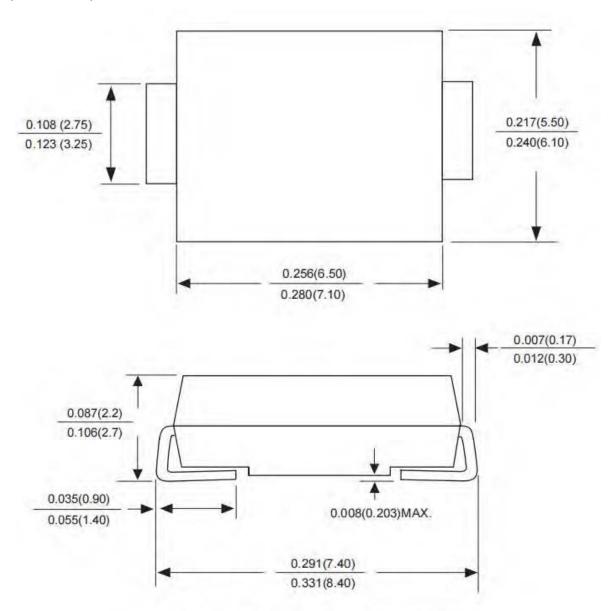


Figure 6. Maximum Non-Repetitive Forward Surge Current Uni-Directional Only





Package Outline Dimensions SMC(DO-214AB)



Dimensions in inches and (millimeters)

SMCJ30(C)AHE3_A/H

Transient Voltage Suppressor

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